			•	
ARTING DIN Signa	l male connecto	nr _ THR	c PL 'us RoH	Soldering instructions
Dily Signa	t mate connects	JI - 11111V	C / LB US complin	THR (Through Hole Reflow) connectors are designed to be used in a reflow oven together with other SMD (Surface Mount Device) components. In this process, called as w
				"Pin in Hole Intrusive Reflow", the connectors are inserted into plated through holes in a comparable way to conventional component mounting. All other components can assembled on the pcb surface.
eral information		-		
erat iiroriiiariori				The length of the connector contacts should be such that they protrude by no more than 1.5 millimetres after insertion to the pcb. Each contact collects solder on its t as it penetrates the solder paste in the hole. So if the contact is too long, this solder would no longer be able to reflow back into the plated through hole by capillary
ign	IEC 60603-2	types: B, 2B, 3B, C, 20	, 3C, M male	action during the soldering process, therefore the quality of the soldered connection would suffer as a result.
of contacts	max. 96			
tact spacing	2,54mm			Quantity of solder paste
t voltage tact resistance	1000V max. 15m0hm			Before the components are assembled, solder paste must be applied to all the solder pads (for connecting surface-mount components) and the plated through holes.
lation resistance	min. 1012Ohm			To ensure that the plated through holes are completely filled, significantly more solder paste must be applied than traditional solder pads on the pcb surface. There are
king current		signal contacts, see derating diagram)		numerous calculation methods available which are complicated to apply. The following rule of thumb has proved valuable in practice:
ponaturo napro	-55°C +125°C			VPaste = 2(VH - VP)
perature range		for reflow soldering		in which: VPaste = Required volume of solder paste
mination technology	SMC with solder p	ins		VH = Volume of the plated through hole
rance & creepage distance	min. 1,2mm each 16–pole max. 15N	20-pole max. 20N		VP = Volume of the connector termination in the hole
rtion and withdrawal force	16-pole max. 15N 30-pole max. 30N	20-pole max. 20N 32-pole max. 30N		Comment: the multiplier "2" compensates for solder paste shrinkage during soldering. For this purpose, it was assumed that 50 % of the paste consists of the actual so
	48-pole max. 45N	64-pole max. 60N	96-pole max. 90N	the other 50 % being soldering aids.
ng cycles	acc. to performanc	e level, see table below		Cross section of solder pins
ile	E102079			
S - compliant	Yes			$A = 0.29 \text{mm}^2 - 0.33 \text{mm}^2$
lfree nlugging	Yes No			8
plugging	, INU			
lator material				
				0,5+0,05
rerial	·	es, glass fiber reinforcement 30%)		<u> </u>
our classification	UL 94-V0	colour deviations and speckles permitt	20	—
rerial group acc. IEC 60664-1	UL 94-VU II (400 <u><</u> CTI < 600			Derating diagram acc. to IEC 60512-5 (Current carrying capacity)
classification	13, F3	·		The current carrying capacity is limited by maximum temperature
	,	,		of materials for inserts and contacts including terminals.
				The current capacity curve is valid for continuous, non
ntact material	.	<u> </u>		interrupted current loaded contacts of connectors when
11 acı				simultaneous power on all contacts is given, without exceeding the maximum temperature.
tact material	Copper alloy	<u> </u>		Control and test procedures according to DIN IEC 60512-5 및
ing termination zone	Sn over Ni			Control and rest procedures according to bits lice obsta-3
ing contact zone	acc. to performanc	e level, see table below		Control and test procedures according to DIN IEC 60512-5
	matic	ng cycles		0.5
nonformacia (1)		ig cycles	alakinakk	
performance level	acc. to IEC 60603-2	complementary	plating contact zone	
	acc. 10 ILC 00003-2	acc. to IEC 60603-2		0 20 40 60 80 100 120 °C
1	500		Au over PdNi over Ni	Temperature [°C]
2	400		Au over PdNi over Ni	<u> </u>
3	50		Au over PdNi over Ni	
	J	500	min. 0,76µm (30µinch) noble metal (alloy) over Ni	
<u> </u>	ΓΛΛ	טטכ		<u> </u>
NM30 (S4)	500		Au over Ni	<u> </u>
NM30 (S4) Au1		500	Au over Ni	
NM30 (S4) Au1 Au2	400	500	min. 0,76µm (30µinch) Au over Ni	All Dimensions in mm Scale Free size tol. Original Size DIN A3 1:1 Ref. Sub.
NM30 (S4) Au1 Au2 Au30	400			1 × 1 × 1
NM30 (S4) Au1 Au2 Au30 Au50	400	500	min. 1,27μm (50μinch) Au over Ni	
NM30 (S4) Au1 Au2 Au30	400		min. 1,27µm (50µinch) Au over Ni min. 1,60µm (70µinch) Au over Ni	All rights reserved Created by Inspected by Standardisation Date State
NM30 (S4) Au1 Au2 Au30 Au50	400	500		All rights reserved Created by Inspected by Standardisation Date State STORIK I FHNERT HOFFMANN 2018-06-28 Final Release
NM30 (S4) Au1 Au2 Au30 Au50 Au70 Au90		500 500 500	min. 1,60µm (70µinch) Au over Ni min. 2,00µm (90µinch) Au over Ni	All rights reserved Created by Standardisation Date State Stork LEHNERT HOFFMANN 2018-06-28 Final Release Department EC PD - DE Title
NM30 (S4) Au1 Au2 Au30 Au50 Au70 Au90		500 500 500	min. 1,60µm (70µinch) Au over Ni	All rights reserved Department EC PD DE
NM30 (S4) Au1 Au2 Au30 Au50 Au70 Au90		500 500 500	min. 1,60µm (70µinch) Au over Ni min. 2,00µm (90µinch) Au over Ni	All rights reserved Created by Standardisation Date State STORCK LEHNERT HOFFMANN 2018-06-28 Final Release

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